## KALFLIX-HT HIGH TEMPERATURE ADHESIVE

KALFLIX-HT is a 100% solids epoxy specifically formulated for high temperature applications. KALFLIX-HT is a general purpose adhesive formulated specifically for the applications of porous materials to clean substrates. Typical applications are for bonding clean metals to each other, or wood, fibreglass, concrete, ceramic tile, pump casings, chutes, etc. The substrates should be sandblasted and washed with KALFLIX solvent before applying KALFLIX-HT.

## APPLICATIONS INSTRUCTIONS

- 1. Prepare surface to be bonded by sandblasting or scarifying to eliminate all surface scale, rust and unclean matter. Wipe with a clean cloth, soaked with solvent. Do not apply adhesive onto substrate that is below 50°F.
- 2. Mix 1 part hardener to 1 part resin on a separate board until uniform in color.
- 3. Apply mix components to surface of tile and surface to be bonded. Press tile onto substrate to evacuate air.
- 4. Do not move tile after 90 minutes or after initial cure.

## TYPICAL PROPERTIES OF KALFLIX-HT HIGH TEMPERATURE ADHESIVE

-Tensile Strength ASTM D-695

-Compressive Strength ASTM D-695

-Impact Strength

-Operating Temperature with 1/2" Tile Applied

to Metal Substrate

-Mix Ratio

-Mixed Color

-Consistency

-Cure Room Temperature

-Weight per Kit (net)

-Coverage

6,000 psi 14,000 psi .21ft. lbs. / in. notch

350°F-400°F 1-1 by Volume Manila (off white) Thick Creamy Paste 4-5 Hours 20 lbs. per kit 25 Sq.Ft. at ½" thick

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